



SOT287-1

plastic small outline package; 32 leads; body width 7.5 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO32
Package type industry code	SO32
Package style descriptive code	SO (small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-119
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

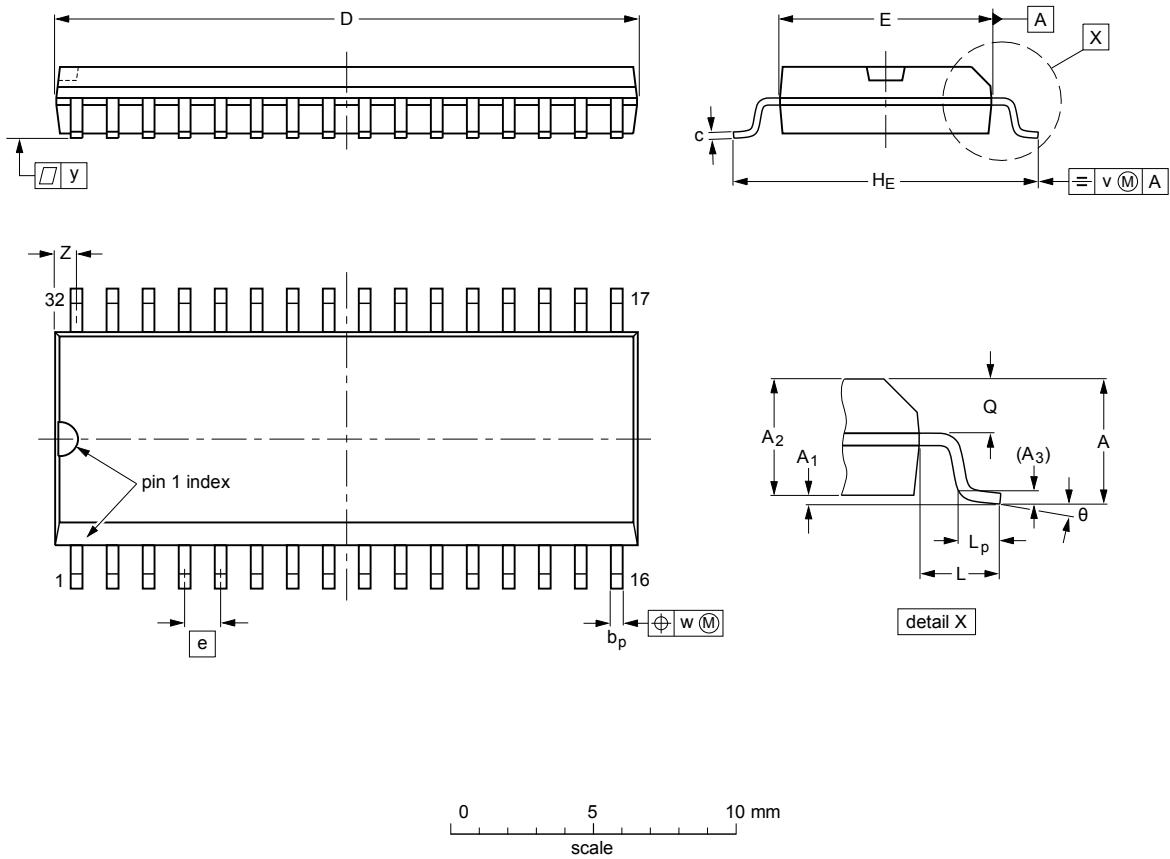
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	20.3	-	20.5	20.7	mm
E	package width	7.4	-	7.5	7.6	mm
A	seated height	[tbd]	-	2.65	2.65	mm
A ₂	package height	2.25	-	2.35	2.45	mm
n ₂	actual quantity of termination	-	-	32	-	



2. Package outline

SO32: plastic small outline package; 32 leads; body width 7.5 mm

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DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.27 0.18	20.7 20.3	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.2 1.0	0.25	0.25	0.1	0.95 0.55	8° 0°
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.02 0.01	0.011 0.007	0.81 0.80	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.047 0.039	0.01	0.01	0.004	0.037 0.022	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT287-1		MO-119				00-08-17 03-02-19

Fig. 1. Package outline SO32 (SOT287-1)

3. Soldering

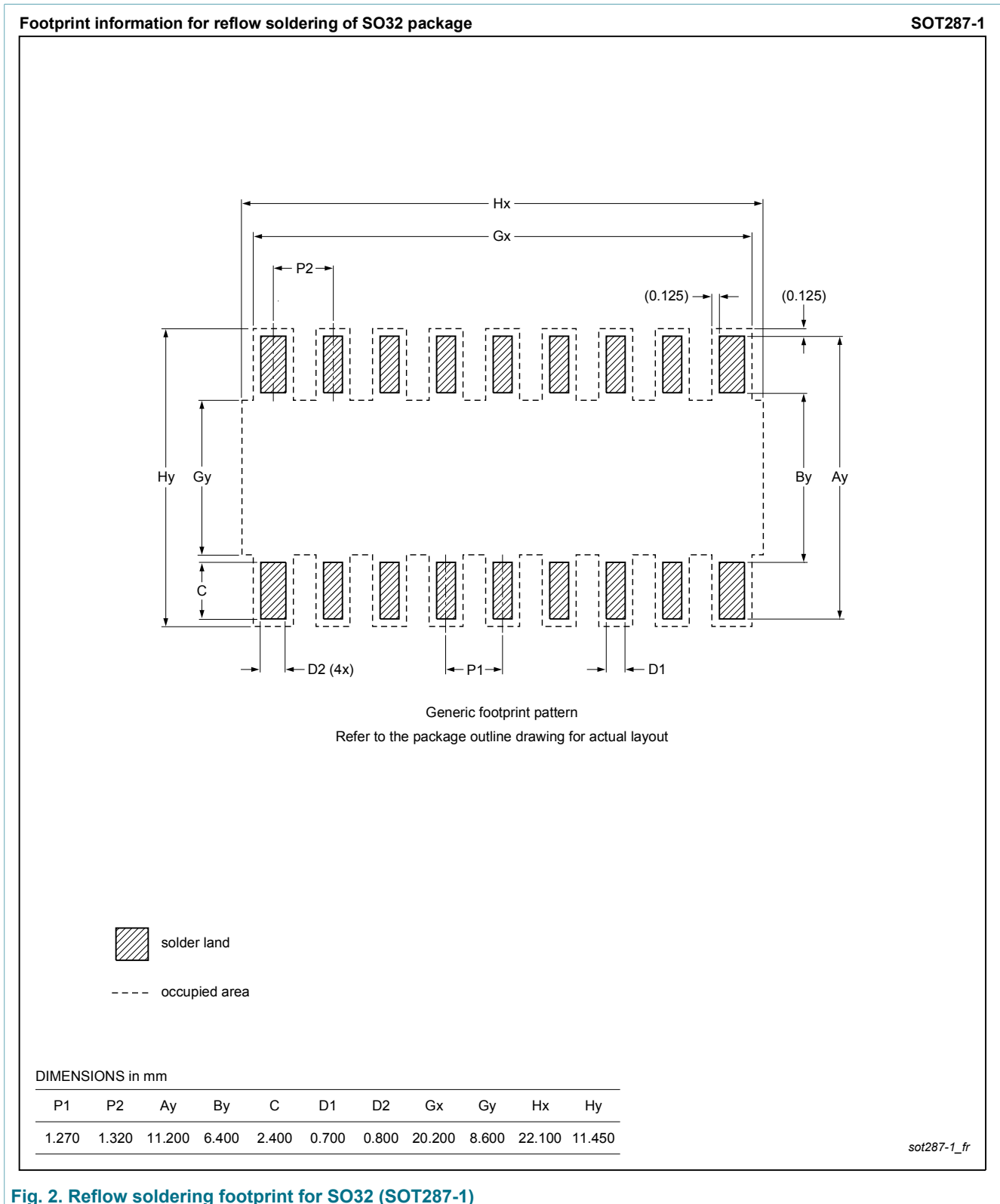


Fig. 2. Reflow soldering footprint for SO32 (SOT287-1)

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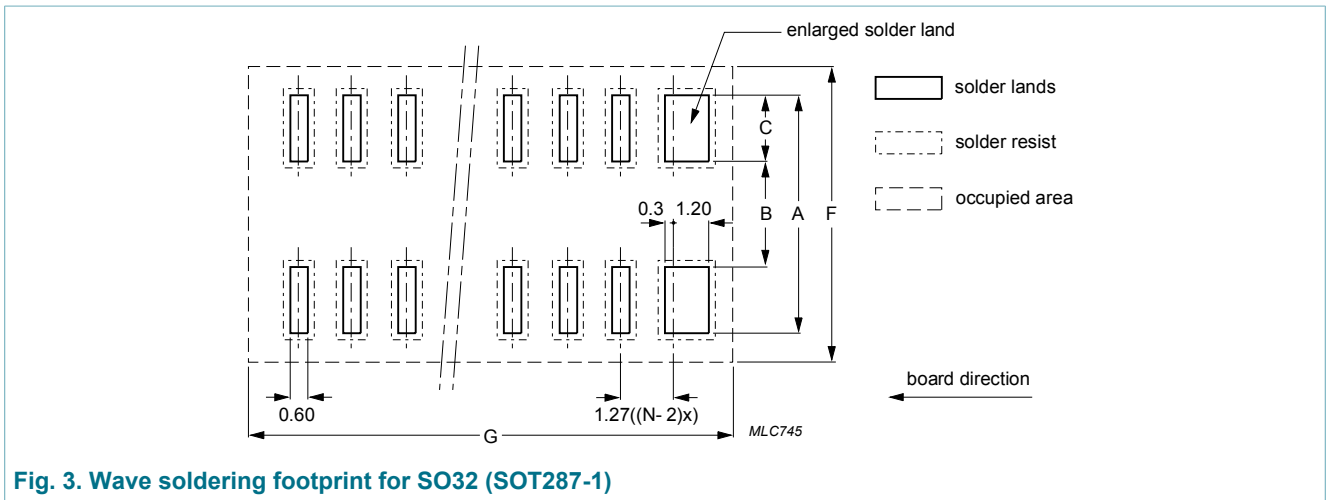


Fig. 3. Wave soldering footprint for SO32 (SOT287-1)

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